2SJ217

Silicon P-Channel MOS FET

HITACHI

November 1996

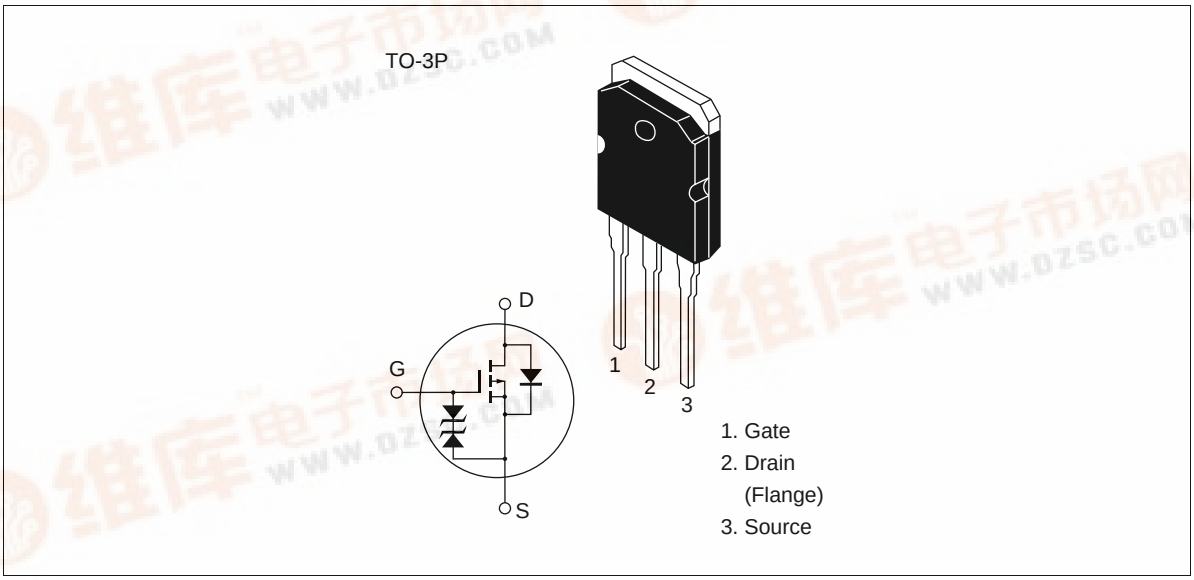
Application

High speed power switching

Features

- Low on-resistance
- High speed switching
- Low drive current
- 4 V gate drive device
  — Can be driven from 5 V source
- Suitable for motor drive, DC-DC converter, power switch and solenoid drive

Outline



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Absolute Maximum Ratings (Ta = 25°C)

Item	Symbol	Ratings	Unit
Drain to source voltage	V_{DSS}	–60	V
Gate to source voltage	V_{GSS}	±20	V
Drain current	I_D	–45	A
Drain peak current	$I_{D(pulse)}$*[1]	–180	A
Body to drain diode reverse drain current	I_{DR}	–45	A
Channel dissipation	Pch*[2]	150	W
Channel temperature	Tch	150	°C
Storage temperature	Tstg	–55 to +150	°C

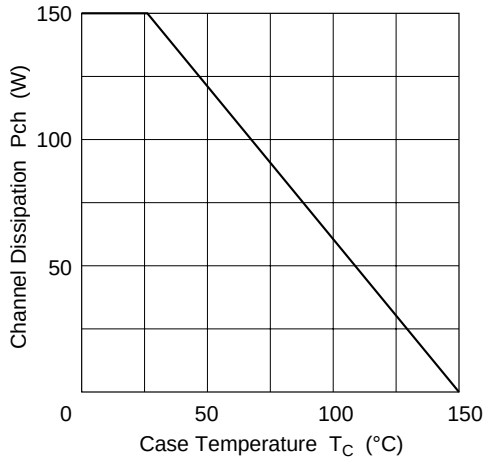
Notes 1. PW ≤ 10 µs, duty cycle ≤ 1%
2. Value at T_C = 25°C

Electrical Characteristics (Ta = 25°C)

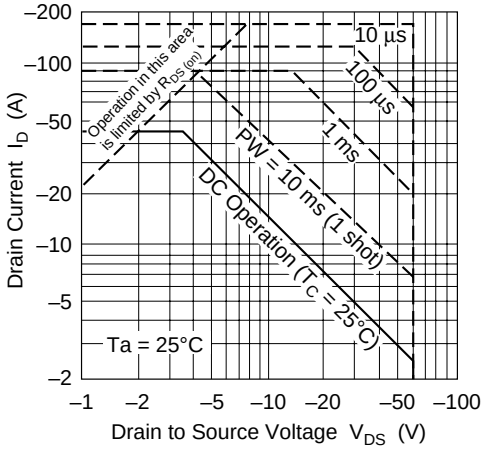
Item	Symbol	Min	Typ	Max	Unit	Test conditions
Drain to source breakdown voltage	$V_{(BR)DSS}$	–60	—	—	V	I_D = –10 mA, V_{GS} = 0
Gate to source breakdown voltage	$V_{(BR)GSS}$	±20	—	—	V	I_G = ±100 µA, V_{DS} = 0
Gate to source leak current	I_{GSS}	—	—	±10	µA	V_{GS} = ±16 V, V_{DS} = 0
Zero gate voltage drain current	I_{DSS}	—	—	–250	µA	V_{DS} = –50 V, V_{GS} = 0
Gate to source cutoff voltage	$V_{GS(off)}$	–1.0	—	–2.0	V	I_D = –1 mA, V_{DS} = –10 V
Static drain to source on state resistance	$R_{DS(on)}$	—	0.033	0.042	Ω	I_D = –20 A, V_{GS} = –10 V*[1]
		—	0.045	0.06		I_D = –20 A, V_{GS} = –4 V*[1]
Forward transfer admittance	$\|y_{fs}\|$	16	25	—	S	I_D = –20 A, V_{DS} = –10 V*[1]
Input capacitance	Ciss	—	3800	—	pF	V_{DS} = –10 V, V_{GS} = 0, f = 1 MHz
Output capacitance	Coss	—	2000	—	pF	
Reverse transfer capacitance	Crss	—	490	—	pF	
Turn-on delay time	$t_{d(on)}$	—	30	—	ns	I_D = –20 A, V_{GS} = –10 V, R_L = 1.5 Ω
Rise time	t_r	—	235	—	ns	
Turn-off delay time	$t_{d(off)}$	—	670	—	ns	
Fall time	t_f	—	450	—	ns	
Body to drain diode forward voltage	V_{DF}	—	–1.35	—	V	I_F = –45 A, V_{GS} = 0
Body to drain diode reverse recovery time	t_{rr}	—	300	—	ns	I_F = –45 A, V_{GS} = 0, di_F/dt = 50 A/µs

Note 1. Pulse test

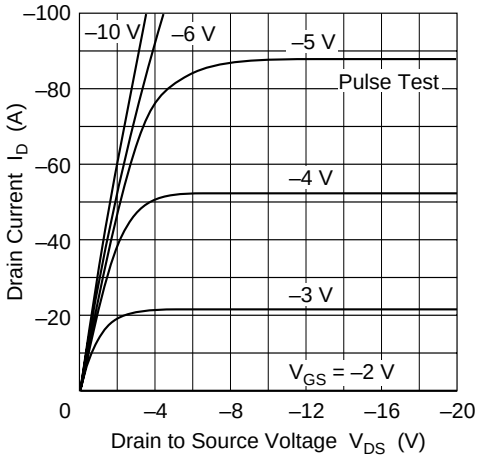
Power vs. Temperature Derating



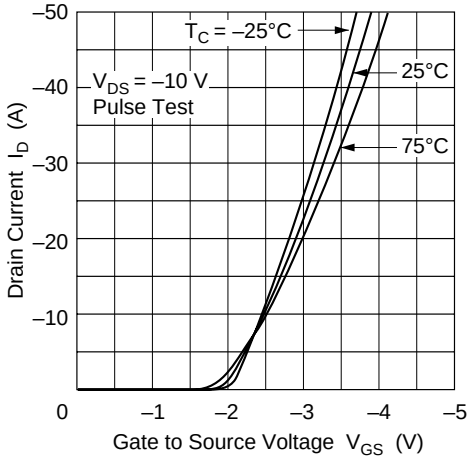
Maximum Safe Operation Area



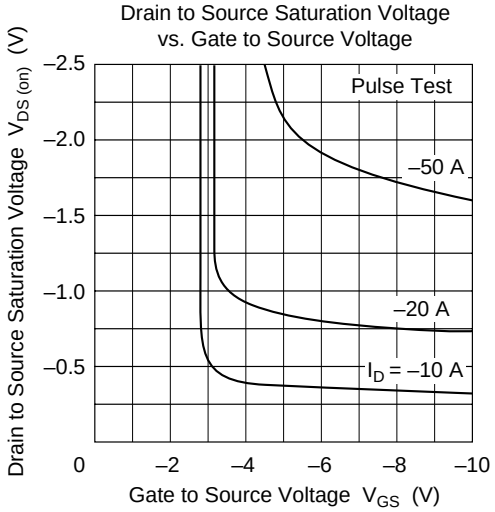
Typical Output Characteristics



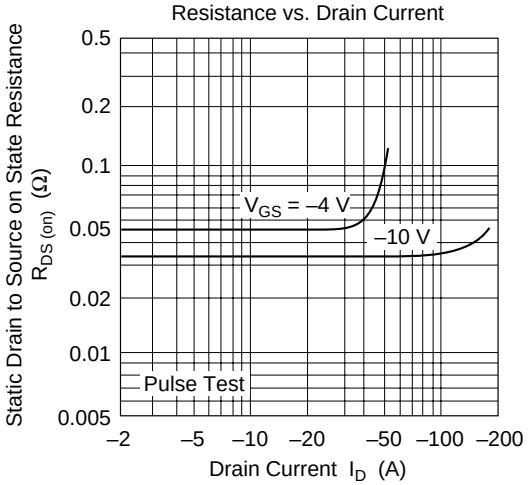
Typical Forward Transfer Characteristics



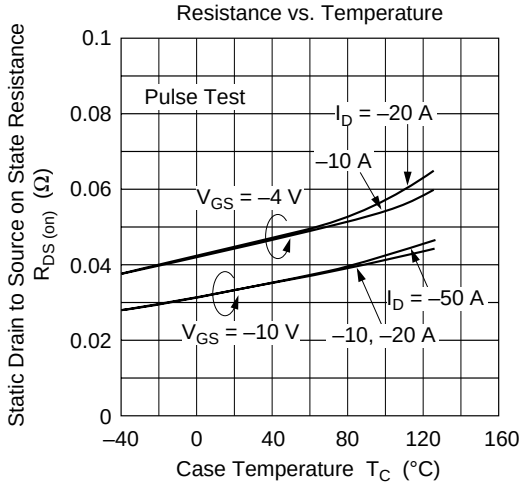
Drain to Source Saturation Voltage vs. Gate to Source Voltage



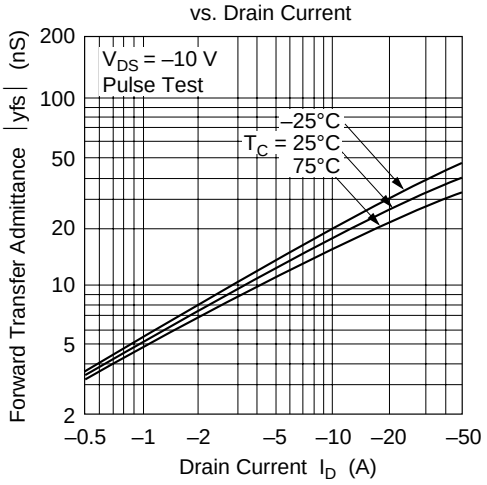
Static Drain to Source on State Resistance vs. Drain Current



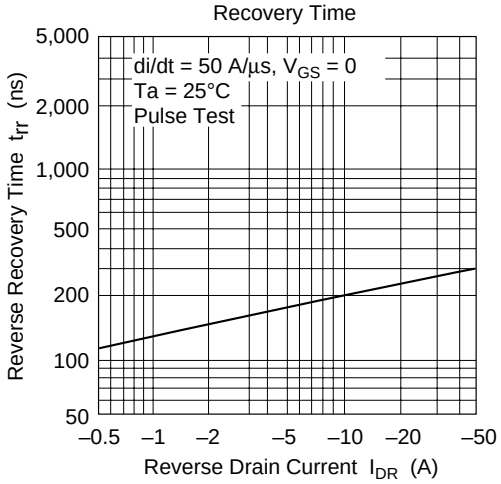
Static Drain to Source on State Resistance vs. Temperature



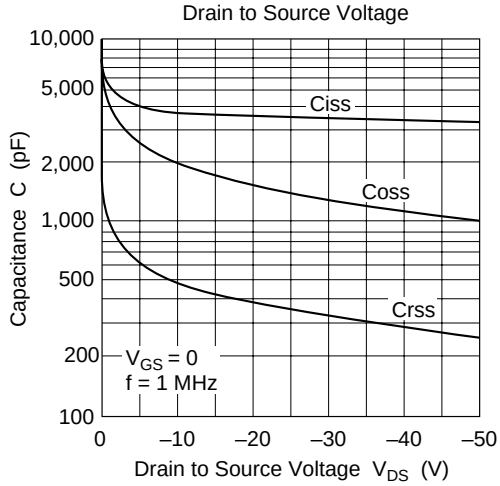
Forward Transfer Admittance vs. Drain Current



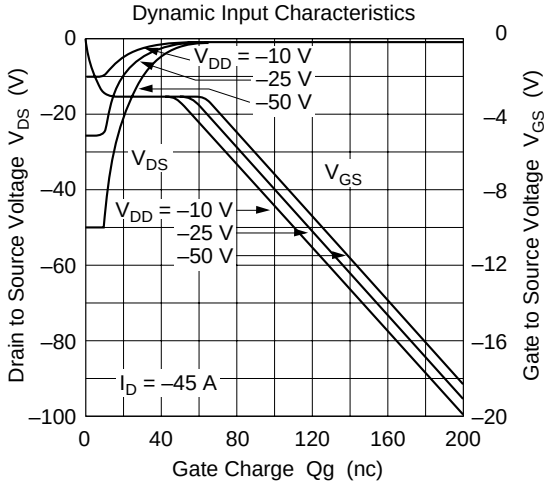
Body to Drain Diode Reverse Recovery Time



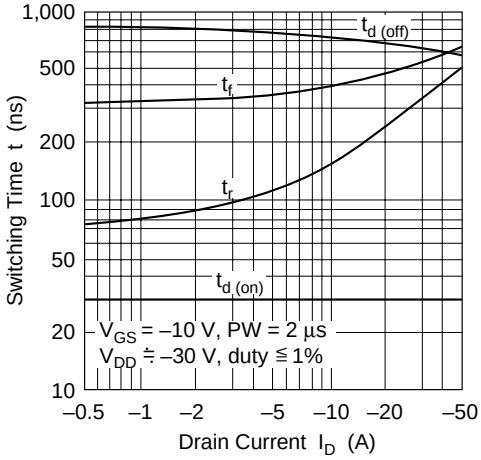
Typical Capacitance vs. Drain to Source Voltage



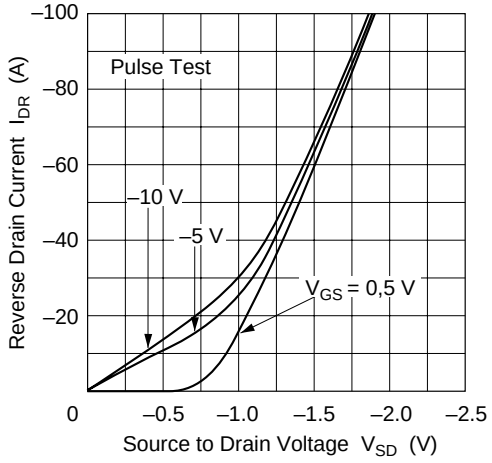
Dynamic Input Characteristics



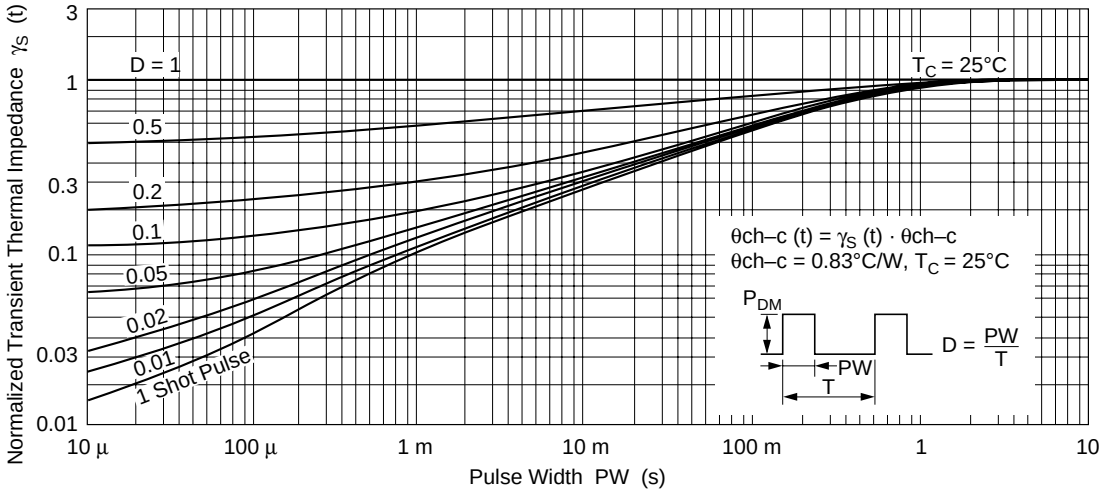
Switching Characteristics



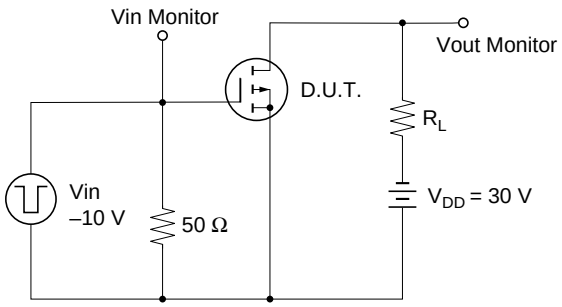
Reverse Drain Current vs.
Source to Drain Voltage



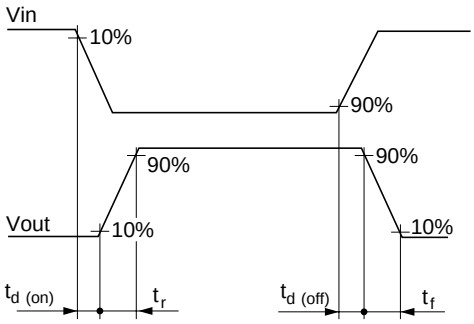
Normalized Transient Thermal Impedance vs. Pulse Width



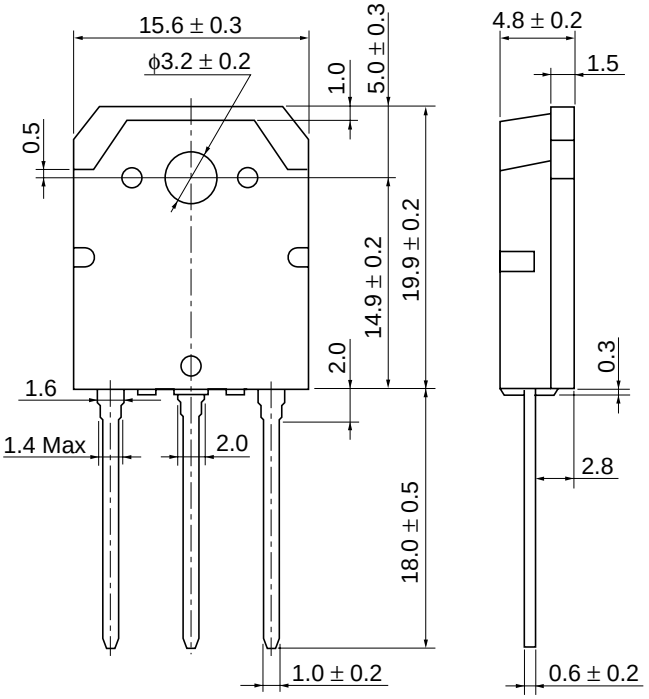
Switching Time Test Circuit

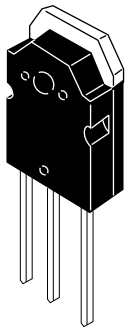


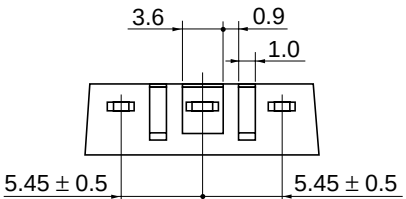
Switching Time Test Waveforms



Unit: mm


15.6 ± 0.3
ϕ3.2 ± 0.2
1.0
5.0 ± 0.3
0.5
14.9 ± 0.2
19.9 ± 0.2
2.0
1.6
1.4 Max
2.0
18.0 ± 0.5
1.0 ± 0.2
4.8 ± 0.2
1.5
0.3
2.8
0.6 ± 0.2




3.6
0.9
1.0
5.45 ± 0.5
5.45 ± 0.5

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HITACHI

Hitachi, Ltd.
Semiconductor & Integrated Circuits.
Nippon Bldg., 2-6-2, Ohte-machi, Chiyoda-ku, Tokyo 100-0004, Japan
Tel: Tokyo (03) 3270-2111 Fax: (03) 3270-5109

URL
NorthAmerica : http:semiconductor.hitachi.com/
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For further information write to:

Hitachi Semiconductor
(America) Inc.
179 East Tasman Drive,
San Jose,CA 95134
Tel: <1> (408) 433-1990
Fax: <1>(408) 433-0223

Hitachi Europe GmbH
Electronic components Group
Dornacher Straße 3
D-85622 Feldkirchen, Munich
Germany
Tel: <49> (89) 9 9180-0
Fax: <49> (89) 9 29 30 00

Hitachi Europe Ltd.
Electronic Components Group.
Whitebrook Park
Lower Cookham Road
Maidenhead
Berkshire SL6 8YA, United Kingdom
Tel: <44> (1628) 585000
Fax: <44> (1628) 778322

Hitachi Asia Pte. Ltd.
16 Collyer Quay #20-00
Hitachi Tower
Singapore 049318
Tel: 535-2100
Fax: 535-1533

Hitachi Asia Ltd.
Taipei Branch Office
3F, Hung Kuo Building. No.167,
Tun-Hwa North Road, Taipei (105)
Tel: <886> (2) 2718-3666
Fax: <886> (2) 2718-8180

Hitachi Asia (Hong Kong) Ltd.
Group III (Electronic Components)
7/F., North Tower, World Finance Centre,
Harbour City, Canton Road, Tsim Sha Tsui,
Kowloon, Hong Kong
Tel: <852> (2) 735 9218
Fax: <852> (2) 730 0281
Telex: 40815 HITEC HX